



Silicon Wafer Japan TC Chapter

Japan Standards Summer Meetings 2024

Thursday, August 29, 2024

SEMI Japan, Tokyo, Japan/ Official Virtual TC Chapter Meeting (Hybrid)

14:00-16:00 JST

AGENDA

1 Welcome/Call to Order

- 1.1 Introductions
- 1.2 Required Elements (Membership Requirements, Antitrust and Intellectual Property Reminders, and Effective Meeting Guidelines)
- 1.3 Agenda Review

2 Review of Previous Meeting Minutes

3 Liaison Report

- 3.1 Japan Regional Standards Committee (JRSC)
- 3.2 Global Coordinating Subcommittee (GCS)
- 3.3 Europe TC Chapter
- 3.4 North America TC Chapter

4 Staff Report

5 Ballot Review

None

6 Subcommittee & Task Force Reports

- 6.1 International Advanced Wafer Geometry Task Force
- 6.2 International/ Japan Test Method Task Force
- 6.3 International Advanced Surface Inspection Task Force
- 6.4 International Polished Wafers Task Force
- 6.5 International Epitaxial Wafers Task Force

6.6 International Annealed Wafers Task Force

6.7 International SOI Wafers Task Force

6.8 International Terminology Task Force

7 Old Business

7.1 Project Period Review

7.2 5-year Review

- SEMI M85-0120, Guide for the Measurement of Trace Metal Contamination on Silicon Wafer Surface by Inductively Coupled Plasma Mass Spectrometry
- SEMI M88-0119, Practice for Sample Preparation Methods for Measuring Minority Carrier Diffusion Length in Silicon Wafers by Surface Photovoltage Methods

8 New Business

8.1 SNARF for Revision to SEMI M62-0317 SPECIFICATION FOR SILICON EPITAXIAL WAFERS

9 Action Item Review

9.1 Open Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
SW20240426-01	Ryuji Takeda (GlobalWafers Japan)	To communicate with Kevin Nguyen (SEMI NA Staff) to put SEMI MF391-0310 on 5-year review process.

9.2 New Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>

10 Next Meeting and Adjournment

10.1 The next meeting is scheduled for <date> at <event/location>.